



SEMICON Southeast Asia (SEMICON SEA)2026 Exhibition Announcement

Takatori Corporation will exhibit at SEMICON Southeast Asia (SEMICON SEA) 2026 to be held from **May 5 to 7, 2026**.

We sincerely look forward to welcoming you to our exhibition locations.

【Exhibition Highlights】

New Model: Panel Level Packaging Machine PLP-700

Takatori will present its latest Panel Level Packaging machine, the **PLP-700**, designed to support panel sizes up to **700 mm × 700 mm**, through panel display.

We will introduce advanced semiconductor manufacturing solutions centered on this latest PLP-700.

For detailed information about the PLP-700, please visit us at SEMICON SEA 2026.

Exhibition Locations:

- Toyo Adtec Co., Ltd
HALL 5-8, LEVEL2, SINGAPORE PAVILION BOOTH NO. 2427
- Millice Sdn Bhd
HALL1-4, LEVEL1, MALAYSIA PAVILION BOOTH NO. 1558

New Model: Multi Wire Saw for 12-inch SiC MWS-SiC12F

Takatori will also present its latest multi-wire saw, the **MWS-SiC12F**, designed for slicing large-diameter ingots up to 12 inches in diameter (maximum supported diameter: 14 inches), through panel displays.

For detailed information about the MWS-SiC12F, please visit us at SEMICON SEA 2026.

Exhibition Location:

- Millice Sdn Bhd
HALL1-4, LEVEL1, MALAYSIA PAVILION BOOTH NO. 1558

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